

III. REMARKS

1. Claims 1-10 remain in the application. Claims 1 and 7 have been amended.

2. Applicants appreciate the courtesies extended by the Examiner during the Examiner's Interview of 4 August 2005.

3. Applicants appreciate the indication that claims 7-10 would be allowable if rewritten in independent form including all the limitations of the base claim and any intervening claims. However, Applicants believe that these claims are patentable as they stand for the reasons stated below.

4. Claims 1-6 are not anticipated by Hamano (US 6,366,463) under 35 USC 102(b).

Hamano fails to disclose or suggest a heat sink arrangement comprising a support means and a pivotable heat sink, where the heat sink is pivoted by the insertion of the equipment module into the support means such that a surface of the heat sink is brought into contact with a surface of the equipment module, as recited by claim 1.

Hamano does not have a heat sink arrangement that includes a support means. In addition, Hamano fails to disclose that the heat sink pivots by the insertion of an equipment module into the support means. Hamano's heat sink 21 is fastened by screws 30 to printed circuit board 15. The heat sink is also fastened to a heat pipe 22, which in turn is fastened to the equipment frame. The heat sink 21 may be rotated away to exchange CPU 16 by unfastening screws 30, however, the heat sink does not pivot when an equipment module is inserted into

a support means. There is no support means as part of the heatsink assembly, and inserting the CPU does not cause the heat sink to pivot. Instead, after the CPU 16 is installed, the heat sink must be rotated downward to make contact with the CPU. Nowhere in Hamano is there disclosure related to the heat sink being pivoted by the insertion of the CPU into a support means.

At least for these reasons, Applicants submit that Hamano fails to anticipate independent claim 1 and dependent claims 2-10.

5. Claims 1-3, 5, and 6 are not anticipated by Yan et al. (US 6,447,322, "Yan") under 35 USC 102(a).

Yan, like Hamano, fails to disclose or suggest the heat sink being pivoted by the insertion of the equipment module into the support means such that a surface of the heat sink is brought into contact with a surface of the equipment module, as recited by claim 1.

In Yan, the electronic assembly 12 is inserted into the holder 14 (see column 2, lines 29-30). The springs 60 are then released (column 2, lines 36-37) and the heat sinks are lowered to make thermal contact with the integrated circuit under test. When testing is complete, the heat sinks are pivoted away from the test position, the electronic assembly 12 is removed from the holder 14, and another assembly is inserted into the holder in a similar manner. There is nothing in Yan related to an arrangement whereby the heat sink is pivoted by insertion of the electronic test assembly into a support means such that the surface of the heat sink is brought into contact with the assembly.

Both Hamano and Yan require the integrated circuit or CPU to be inserted into its holder and then, in a separate step, the heat sinks to be moved into place to make contact with the integrated circuit or CPU. This is in contrast to the present invention as recited by claim 1 whereby it is the action of inserting the equipment module into the support means that causes the heat sink to be pivoted in such a way that a surface of the heat sink is brought into contact with a surface of the equipment module.

At least for these reasons, Applicants respectfully submit that Yan fails to anticipate independent claim 1 and dependent claims 2, 3, 5, and 6.

6. Claim 4 is patentable over the combination of Yan in view of Garner et al. (US 5,822,187, "Garner") under 35 USC 103(a).

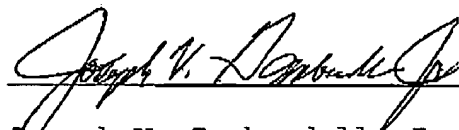
Claim 4 depends from claim 1.

Garner fails to supply the features of claim 1 missing from Yan, that is, the heat sink being pivoted by the insertion of the equipment module into the support means such that a surface of the heat sink is brought into contact with a surface of the equipment module, as recited by claim 1. Therefore, claim 4 is patentable over the combination of Yan and Garner.

It is respectfully submitted that all of the claims present in the application are clearly novel and patentable, and are in proper form for allowance. Accordingly, favorable consideration and allowance is respectfully requested. Should any unresolved issues remain, the Examiner is invited to call Applicants' attorney at the telephone number indicated below.

The Commissioner is hereby authorized to charge payment for any fees associated with this communication or credit any over payment to Deposit Account No. 16-1350.

Respectfully submitted,


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12 August 2005
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